DNR-MIL

12- Slot, Military-Grade I/O Rack

- Military/Rugged 38999 connectivity (keying optional)
- 100% COTS solution
- Supported by over 90 standard DNR-series I/O boards
- 5 g vibration, 100 g shock, sealed to IP66
- Dual GigE ports (control and diagnostic)
- Designed for MIL-STD-461/810/1275 compliance
- Extensive built-in system diagnostics
- PowerDNR, UEIPAC, UEISIM & UEIMODBUS configurations
- No rotary cooling devices
- Extensive software support including Windows, Linux, QNX, RTX and more
- VxWorks support available in embedded or hosted configurations

General Description

The DNR-MIL is the latest deployment of UEI's popular RACKtangle® architecture. Though the original RACKtangles are quite rugged, the DNR-MIL series takes ruggedness to the extreme. Designed for use in the toughest environments, the new DNR-MIL is an ideal solution for military and aerospace deployments. The form factor is also ideal for a huge assortment of commercial applications including use on oil drilling platforms and refineries, heavy machinery, outdoor test stands and any other I/O application that will be exposed to the elements. All connectivity is through ROHS compliant 38999 connectors. Keyed connectors are available as an option.

Electronically, the DNR-MIL is identical to the standard DNR Series RACKtangle except for power supply hold-up and protection circuitry. (This power supply conditioning is required in order to meet MIL-STD-1275.) The DNR-MIL uses our standard DNR-series board (e.g. DNR-AI-217 or DNR-1553-553). With over 50 unique I/O boards and 12 slots available there's sure to be a configuration perfectly matching your application.

The new DNR-MIL is designed to meet the most commonly required elements of MIL-STD-461 and -810 and is sealed to at least IP66/NEMA6 standards. All this is housed in a compact 17.5" W x 8.125" D x 7.0" H chassis, weighing less than 22 pounds and typically consuming less than 40 W. In addition, no rotary cooling fans are used in the design which maximizes MTBF and mechanical reliability. All internal printed circuit boards are conformal coated to ensure the highest reliability.

The DNR-MIL is available in four different deployment options. In PowerDNA, UEIPAC, UEISIM and UEIMODBUS.

PowerDNA: DNR-MIL

In PowerDNA mode, the RACKtangle operates as a slave I/O device, running under the control of a host PC. All application code in this mode is created and run on the host. PowerDNR mode offers almost unprecedented software support including:

- All popular operating systems including Windows, Linux, VxWorks, QNX, RTX and InTime
- All popular programming languages including VB, VB.NET, C, C#, C++, JAVA
- All popular application packages including MATLAB, Simulink, LabVIEW, DasyLAB and more.



The DNR-MIL provides 12 I/O slots and uses standard DNR-series I/O boards (e.g. DNR-AI-217). It is available in the standard PowerDNR configuration or as a UEIPAC or UEISIM.

UEIPAC 1200-MIL

EXTENDED

10

When deployed as a UEIPAC, the standard firmware running on a RACKtangle is replaced by either a Linux or VxWorks operating system. The user then writes the Linux/VxWorks application that runs on the DNR-MIL. In this mode the DNR-MIL can run fully stand-alone, or may be linked to a SCADA host via the Ethernet.

UEISIM 1200-MIL

Simulink users will appreciate the ability to use Simulink coder to compile and deploy their models on the UEISIM hardware. It's an ideal platform for testing models on actual hardware. Once the model is proven, it can be deployed using the exact same hardware.

UEIMODBUS 1200-MIL

Users needing a compact, rugged Modbus TCP I/O slave will appreciate UEIMODBUS. The rugged, IP66/NEMA6 sealed DNR-MIL allows you to deploy your I/O system in the field, without any additional enclosure and protection.

The DNR-MIL platform is 100% COTS and supported by UEI's family of over 90 compatible analog, digital and interface I/O boards, including analog inputs up to 24-bits, thermocouples, RTDs, ICP/IEPE, ARINC-429/453/708, MIL-STD-1553, CAN, RVDT/LVDT, synchro/resolver, RS-232/422/485, strain gauge, quadrature encoder, high-voltage analog outputs (up to 115 VDC) with high drive analog output (up to 200 mA), function generator outputs and more.

Whether your application is on a ship or boat, in an aircraft, in a rocket, on an outdoor test cell, on an oil platform or simply going to be left outside and exposed to the elements, the DNR-MIL is an ideal solution. Of course, if you need fewer I/O, you should consider the 4-slot 6.2" W x 8.7" D x 7.1" H DNA-MIL Cube, which offers many of the same features and options, with slots for up to 4 I/O boards in a much smaller chassis.

Technical Specifications

DNR-MIL (Power DNA mode)

DIAR-MIL (FUWEI DIA MIUUE)			
Computer Interface	PPCx-1G series GigE RACKtangles		
Primary Ethernet Port	10/100/1000Base-T, 38999 connector		
Diagnostic Port	10/100/1000Base-T, 38999 connector		
Configuration/Serial Port	RS-232, 38999 connector		
Synchronization	 DNR-SYNC-1G series cables and boards provide both clock and trigger sync signals. DNR-IRIG-650 board provides IRIG and GPS time synchronization 		
I/O Board Support			
Series supported	All DNR-series boards		
Processor/system			
CPU	Freescale 8347, 400 MHz, 32-bit		
Memory (RAM)	256 MB		
Memory (Flash)	32 MB		
Host Communications			
Distance from host	100 meters max, CAT5 cable		
Ethernet data transfer rate	20 megabyte per second		
Analog data transfer rate	>6 megasample per second. Capable of sustained transfer in any RACKtangle configuration		
DMAP I/O mode	Update >1,000 I/O channels at 4 kHz, guaranteed		
Physical Dimensions / Weight			
12 I/O slots	DNR-MIL: 17.5" W x 8.1" D x 7.0" H, 22 lbs.		
Environmental*			
Environmental* Electrical Isolation	350 Vrms		
	350 Vrms -40 °C to 70 °C		
Electrical Isolation			
Electrical Isolation Temperature (operating)	-40 °C to 70 °C		
Electrical Isolation Temperature (operating) Temperature (storage)	-40 °C to 70 °C -40 °C to 85 °C		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64)	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6)	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock (IEC 60068-2-27)	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock (IEC 60068-2-27) Altitude	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock (IEC 60068-2-27) Altitude EMI/RFI	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock (IEC 60068-2-27) Altitude EMI/RFI Power Requirements	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations 70,000 feet, maximum Designed to meet MIL-STD-461 9–36 VDC (115/220 VAC adaptor		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock (IEC 60068-2-27) Altitude EMI/RFI Power Requirements Voltage	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations 70,000 feet, maximum Designed to meet MIL-STD-461 9–36 VDC (115/220 VAC adaptor available)		
Electrical Isolation Temperature (operating) Temperature (storage) Humidity Vibration (IEC 60068-2-64) (IEC 60068-2-6) Shock (IEC 60068-2-27) Altitude EMI/RFI Power Requirements Voltage Power	-40 °C to 70 °C -40 °C to 85 °C 0 to 95%, non-condensing MIL-STD-810G plus the IEC specs below 10–500 Hz, 5 g (rms), Broad-band random 10–500 Hz, 5 g, Sinusoidal MIL-STD-810G plus the IEC stds below 100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations 70,000 feet, maximum Designed to meet MIL-STD-461 		

Also available in the UEIMODBUS and UEIOPC-UA Configurations!

UEIPAC 1200-MIL

Computer Interface	PPCx-1G series GigE RACKtangles
Primary Ethernet Port	10/100/1000Base-T, 38999 connector
Diagnostic Port*	10/100/1000Base-T, 38999 connector *Alternatively can be teamed/bonded with primary port.
Configuration/Serial Port	RS-232, 38999 connector
USB Port	USB 2.0 fully supported
Synchronization Options	 DNR-SYNC-1G series cables and boards provide both clock and trigger sync signals. DNR-IRIG-650 board provides IRIG and GPS time synchronization PTP client provides software implementation of IEEE-1588
I/O Board Support	
Series Supported	All DNR-series boards
Software / Operating System	
Embedded OS	Linux, kernel 2.6.x (VxWorks Available)
Real-time support	Xenomai RTOS support
Dev Language	C/C++, Eclipse IDE support,
Dev Environments	Linux PC or Cygwin Windows environment
EPICS CAS interface	Yes
SNMP Library	Yes
OS Royalties	None
Processor/system	
CPU	Freescale 8347, 400 MHz, 32-bit
Memory	256 MB (128 MB available for application software)
FLASH memory	32 MB (16 MB available for user applications)
USB drive interface	Standard USB 2.0 port
Physical Dimensions	
12 I/O slots	17.5" W x 8.1" D x 7.0" H, 22 lbs.
Environmental	
Electrical Isolation	350 Vrms
Temperature (operating)	-40 °C to 70 °C
Temperature (storage)	-40 °C to 85 °C
Humidity	0 to 95%, non-condensing
Vibration	MIL-STD-810G plus the IEC specs below
(IEC 60068-2-64)	10–500 Hz, 5 g (rms), Broad-band random
(IEC 60068-2-6)	10–500 Hz, 5 g, Sinusoidal
Shock	MIL-STD-810G plus the IEC stds below
(IEC 60068-2-27)	100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations
Altitude	70,000 feet, maximum
EMI/RFI	Designed to meet MIL-STD-461
Power Requirements	
Voltage	9 - 36 VDC (115/220 VAC adaptor available)
Power	12 Watts (not including I/O boards)
Power Quality requirement	Designed to meet MIL-STD-1275
Reliability	
MTBF	130,000 hours

Technical Specifications

UEISIM 1200-MIL

Computer InterfacePPCx-1G series GigE RACKtanglesPrimary Ethernet Port10/100/1000Base-T, 38999 connectorDiagnostic Port10/100/1000Base-T, 38999 connectorDaisy chain outputn/aOptional Interfacen/aConfiguration/Serial PortUSB 2.0 fully supportedSynchronizationDNR-SYNC-1G series cables and boards provide both clock and trigger sync signalsI/O Board SupportSeries supportedAll DNR-series boardsMATLABSoftware RequirementsMATLABMATLABVersion 2007b or greaterSamulinkVersion 7.0 or greaterReal-Time WorkshopVersion 7.0 or greaterSoftware / Operating SystemLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev LanguageCProcessor/system256 MB (128 MB available for application software)USB drive interfaceStandard USB 2.0 portPhysical Dimensions250 MS121/O slots17.5" H x 8.1" D x 7.0" H, 22 lbs.Environmental350 VrmsTemperature (operating)-40 °C to 75 °CProgreation350 VrmsTemperature (storage)40 °C to 85 °CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-64)10-500 Hz, 5 g (ms), Broad-band random(IEC 60068-2-64)10-500 Hz, 5 g (ms), Broad-band random(IEC 60068-2-67)10-500 Hz, 5 g (ms), Broad-band random(IEC 60068-2-67)10-500 Hz, 5 g (ms), Broad-band random(IEC 60068			
Diagnostic Port10/100/1000Base-T, 38999 connectorDaisy chain outputn/aOptional Interfacen/aConfiguration/Serial PortRS-232, 38999 connectorUSB PortUSB 2.0 fully supportedSynchronizationDNR-SYNC-1G series cables and boards provide both clock and trigger sync signals <i>I/O Board Support</i> Series supportedSeries supportedAll DNR-series boardsSoftware RequirementsVersion 7.0 or greaterMATLABVersion 7.0 or greaterSoftware / Operating SystemEmbedded OSEmbedded OSLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev EnvironmentsSimulink / RTW with Cygwin environment on a Windows PCProcessor/systemCCPUFreescale 8347, 400 MHz, 32-bitVBB drive interfaceStandard USB 2.0 portPhysical Dimensions17.5" H x 8.1" D x 7.0" H, 22 lbs.Environmental350 VrmsTemperature (operating)-40 °C to 85 °CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-64)10-500 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-27)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30g, 11 ms half sine, 18 shocks at 6	Computer Interface	PPCx-1G series GigE RACKtangles	
Daisy chain outputn/aOptional Interfacen/aConfiguration/Serial PortRS-232, 38999 connectorUSB PortUSB 2.0 fully supportedSynchronizationDNR-SYNC-IG series cables and boards provide both clock and trigger sync signals//O Board SupportAll DNR-series boardsSoftware RequirementsVersion 2007b or greaterSimulinkVersion 7.0 or greaterReal-Time WorkshopVersion 7.0 or greaterSoftware / Operating SystemEmbedded OSEmbedded OSLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev LanguageCProcessor/systemSoftwareCPUFreescale 8347, 400 MHz, 32-bitMemory256 MB (128 MB available for application software)USB drive interfaceStandard USB 2.0 portPhysical Dimensions250 VmsTemperature (operating)-40 °C to 70 °CTemperature (operating)-40 °C to 70 °CTemperature (operating)-40 °C to 70 °CTemperature (storage)-40 °C to 70 °CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-67)10-S00 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-27)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms	Primary Ethernet Port	10/100/1000Base-T, 38999 connector	
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'RS-232, 38999 connectorUSB PortUSB 2.0 fully supportedSynchronizationDNR-SYNC-1G series cables and boards provide both clock and trigger sync signalsI/O Board SupportSeries supportedAll DNR-series boardsSoftware RequirementsMATLABVersion 2.0 or greaterSimulinkVersion 7.0 or greaterReal-Time WorkshopVersion 7.0 or greaterSoftware / Operating SystemEmbedded OSLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev EnvironmentsSimulink / RTW with Cygwin environment on a Windows PCProcessor/systemCPUFreescale 8347, 400 MHz, 32-bitMemory256 MB (128 MB available for application software)USB drive interfaceStandard USB 2.0 portPhysical Dimensions12 I/O slots17.5" H x 8.1" D x 7.0" H, 22 lbs.Environmental350 VrmsTemperature (operating)40 °C to 70 °CTemperature (storage)40 °C to 85 °CHumidity0to 95%, non-condensingVibration10-500 Hz, 5 g, SinusoidalShockML-STD-810G plus the IEC specs below(IEC 60068-2-6)10-500 Hz, 5 g, SinusoidalShockML-STD-810G plus the IEC stds below(IEC 60068-2-27)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 30 g, 30	Daisy chain output	n/a	
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SynchronizationDNR-SYNC-TG series cables and boards provide both clock and trigger sync signalsSynchronizationJONR-SYNC-TG series cables and boards provide both clock and trigger sync signalsJONR-SYNC-TG series cables and boards provide both clock and trigger sync signalsSoftware SupportAll DNR-series boardsSoftware RequirementsVersion 7.0 or greaterSoftware / Operating SystemEmbedded OSLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev LanguageCProcessor/systemCPUFreescale 8347, 400 MHz, 32-bitMemory256 MB (128 MB available for application software)USB drive interfaceStandard USB 2.0 portPhysical Dimensions12 I/O slots17.5" H x 8.1" D x 7.0" H, 22 lbs.EnvironmentalElectrical Isolation350 VrmsTemperature (operating)4-0"C to 70 "CTemperature (storage)4-0"C to 85 "CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-64)10-500 Hz, 5 g (rms), Broad-band random(IEC 60068-2-64)10-500 Hz, 5 g (rms), Broad-band random<	Configuration/Serial Port	RS-232, 38999 connector	
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Series supportedAll DNR-series boardsSoftware RequirementsVersion 2007b or greaterMATLABVersion 7.0 or greaterSimulinkVersion 7.0 or greaterReal-Time WorkshopVersion 7.0 or greaterSoftware / Operating SystemInux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev LanguageCDev EnvironmentsSimulink / RTW with Cygwin environment on a Windows PCProcessor/systemStandard USB 2.0 portCPUFreescale 8347, 400 MHz, 32-bit (128 MB available for application software)USB drive interfaceStandard USB 2.0 portPhysical Dimensions12 I/O slots12 I/O slots7.7.5" H x 8.1" D x 7.0" H , 22 lbs.Environmental40 °C to 70 °CEnvironmental40 °C to 85 °CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-6)10-500 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-6)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientationsAltitude70,000 feet, maximumEMIRE9-36 VDC (115/220 VAC adaptor available)Power Quality requirementDesigned to meet MIL-STD-1275Power Quality requirementDesigned to meet MIL-STD-1275Reliability0Designed to meet MIL-STD-1275	Synchronization	provide both clock and trigger sync	
Software RequirementsMATLABVersion 2007b or greaterSimulinkVersion 7.0 or greaterReal-Time WorkshopVersion 7.0 or greaterSoftware / Operating SystemLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev EnvironmentsSimulink / RTW with Cygwin environment on a Windows PCProcessor/systemCCPUFreescale 8347, 400 MHz, 32-bitMemory256 MB (128 MB available for application software)USB drive interfaceStandard USB 2.0 portPhysical DimensionsT12 I/O slots17.5" H x 8.1" D x 7.0" H, 22 lbs.Environmental40 °C to 70 °CEnerature (operating)-40 °C to 85 °CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-6)10-500 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-6)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orie	I/O Board Support		
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SimulinkVersion 7.0 or greaterReal-Time WorkshopVersion 7.0 or greaterSoftware / Operating SystemEmbedded OSEmbedded OSLinux, kernel 2.6.x, Xenomai RTOS supportDev LanguageCDev EnvironmentsSimulink / RTW with Cygwin environment on a Windows PCProcessor/systemCCPUFreescale 8347, 400 MHz, 32-bitMemory256 MB (128 MB available for application 	Software Requirements		
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Temperature (storage)-40 °C to 85 °CHumidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-64)10-500 Hz, 5 g (rms), Broad-band random(IEC 60068-2-6)10-500 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-77)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientationsAltitude70,000 feet, maximumEMI/RFIDesigned to meet MIL-STD-461Power Requirements9-36 VDC (115/220 VAC adaptor available)Power Quality requirementDesigned to meet MIL-STD-1275Reliability	Electrical Isolation	350 Vrms	
Humidity0 to 95%, non-condensingVibrationMIL-STD-810G plus the IEC specs below(IEC 60068-2-64)10-500 Hz, 5 g (rms), Broad-band random(IEC 60068-2-6)10-500 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-27)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientationsAltitude70,000 feet, maximumEMI/RFIDesigned to meet MIL-STD-461Power Requirements9-36 VDC (115/220 VAC adaptor available)Power Quality requirementDesigned to meet MIL-STD-1275ReliabilityEmile State	Temperature (operating)	-40 °C to 70 °C	
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(IEC 60068-2-6)10-500 Hz, 5 g, SinusoidalShockMIL-STD-810G plus the IEC stds below(IEC 60068-2-27)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientationsAltitude70,000 feet, maximumEMI/RFIDesigned to meet MIL-STD-461Power Requirements9-36 VDC (115/220 VAC adaptor available)Power Quality requirementDesigned to meet MIL-STD-1275Reliability	Vibration	MIL-STD-810G plus the IEC specs below	
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(IEC 60068-2-27)100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientationsAltitude70,000 feet, maximumEMI/RFIDesigned to meet MIL-STD-461Power Requirements9–36 VDC (115/220 VAC adaptor available)Power Quality requirement12 W (not including I/O boards)Power Quality requirementDesigned to meet MIL-STD-1275Reliability100 g, 3 ms half sine, 18 shocks at 6 orientations; 30 g, 11 ms half sine, 18 shocks at 6 orientations; 0 orientations	Shock	MIL-STD-810G plus the IEC stds below	
6 orientations Altitude 70,000 feet, maximum EMI/RFI Designed to meet MIL-STD-461 Power Requirements 9–36 VDC (115/220 VAC adaptor available) Power 9–36 VDC (115/220 VAC adaptor available) Power Quality requirement Designed to meet MIL-STD-1275 Reliability	(IEC 60068-2-27)	100 g, 3 ms half sine, 18 shocks at 6 orientations;	
EMI/RFI Designed to meet MIL-STD-461 Power Requirements 9–36 VDC (115/220 VAC adaptor available) Power 9–36 VDC (115/220 VAC adaptor available) Power Quality requirement 12 W (not including I/O boards) Power Quality requirement Designed to meet MIL-STD-1275 Reliability		6 orientations	
Power Requirements Voltage 9–36 VDC (115/220 VAC adaptor available) Power 12 W (not including I/O boards) Power Quality requirement Designed to meet MIL-STD-1275 Reliability 10 Minimum Statement	Altitude	70,000 feet, maximum	
Voltage9–36 VDC (115/220 VAC adaptor available)Power12 W (not including I/O boards)Power Quality requirementDesigned to meet MIL-STD-1275Reliability	EMI/RFI	Designed to meet MIL-STD-461	
available) Power 12 W (not including I/O boards) Power Quality requirement Designed to meet MIL-STD-1275 Reliability	Power Requirements		
Power Quality requirement Designed to meet MIL-STD-1275 Reliability	Voltage		
Reliability	Power	12 W (not including I/O boards)	
	Power Quality requirement	Designed to meet MIL-STD-1275	
MTBF >100,000 hours	Reliability		
	MTBF	>100,000 hours	

Cables, Connectors & screw-terminal panels

Connectors

All connections to the DNR-MIL are made through standard, COTS, nickel plated 38999 connectors. I/O board connections are made through 128-pin connectors where each I/O board utilizes up to 62 of the 128 pins. The Ethernet, USB, diagnostic Serial, Sync, and hardware reset connections are via 37-pin connectors. Power supply and an auxiliary synch bus connections are through a 13-pin connector. The 128 pin connectors can be optionally keyed to eliminate cable connection errors. To add the keyed connectors add the following to your order.

DNR-38999-KEY Clocked/Keyed connectors (N, A, B, C, D, and E keys)

Cables

Though most customers will design custom cables for their deployed systems, customers working on prototypes and/or those building "one of" systems may desire the ability to connect to the DNR-MIL using more traditional, commercial connections (e.g. RJ-45 for the Ethernet ports).

For these customers UEI offers a complete array of cables and screw terminal panels that will provide direct access to all signals routed in and out of the chassis.

LAN/Power Cables

DNA-CBL-LAN-06 Communications cable

6 foot cable connecting the 37-pin LAN/COM/USB port connector to standard commercial connectors. Ethernet ports come out to RJ-45, the serial port to a DB-9 and the USB ports to standard USB jacks.

DNA-CBL-1315-03 Power supply cable

Connects the 13-pin power/sync connector to a standard female DB-15 connector.

I/O board cables

Each 128 pin I/O 38999 connector provides the I/O connectivity for two I/O slots within the DNR-MIL. UEI I/O boards utilize either 37- or 62-pin D connectors and these connectors are mapped as follows.

The left I/O slot (even slot #) maps to pins 1-62 on the 128 pin 38999. The right I/O slot (even slot #) is mapped to pins 65-126 on the 38999. Note that the 37-pin based boards simply do not use pins 38-62. For this reason, most applications can standardize on 62-pin cables and screw terminal panels and simply ignore "no connection" pins. The exception to this is the STP boards that have been specifically designed for use with 37-pin boards (e.g. DNA-STP-207TC). For these boards 37-pin are also available. As some I/O slots may not be utilized, cables with a single 37-pin or 62-pin D connector are also available.

The following cables provide the same I/O connectivity as the standard, commercial DNA-CBL-37S and DNA-CBL-62 series cables.

DNA-CBL-12862-05: 5 ft male 128-pin 38999 to 2x DB-62M DNA-CBL-12837-05: 5 ft male 128-pin 38999 to 2x DB-37F DNA-CBL-6237M-05: 5 ft male ROHS 128-pin 38999 to 1x DB-37F and 1x DB-62M DNA-CBL-62M-03: 3 ft male 128-pin 38999 to 1x DB-62M

DNA-CBL-37M-03: 3 ft male 128-pin 38999 to 1x DB-37F

Screw Terminal Panels

DNA-STP-37	Standard 37-pin screw terminal panel, suitable for use with all 37-pin I/O boards and cables.
DNA-STP-62	Standard 62-pin screw terminal panel, suitable for use with all 62-pin I/O boards and cables.
DNA-STP-3762	Standard 37-pin screw terminal panel, providing both 37- and 62-pin connectors and suitable for use with any combination of I/O board.

38999 Connector Pinouts

128-pin I/0 — mating connector required: D38999/26FJ35PN



Pin #	I/O slot	Board Pin
1	1	1
2	1	2
3	1	3
4	1	4
5	1	5
6	1	6
7	1	7
8	1	8
9	1	9
10	1	10
11	1	11
12	1	12
13	1	13
14	1	14
15	1	15
16	1	16
17	1	17
18	1	18
19	1	19
20	1	20
21	1	21
22	1	22
23	1	23

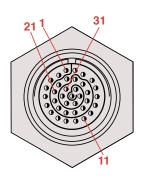
Din # 1/O slat Deard Din

Pin #	I/O slot	Board Pin
24	1	24
25	1	25
26	1	26
27	1	27
28	1	28
29	1	29
30	1	30
31	1	31
32	1	32
33	1	33
34	1	34
35	1	35
36	1	36
37	1	37
38*	1	38
39	1	39
40	1	40
41	1	41
42	1	42
43	1	43
44	1	44
45	1	45
46	1	46

Pin #	I/O slot	Board Pin
47	1	47
48	1	48
49	1	49
50	1	50
51	1	51
52	1	52
53	1	53
54	1	54
55	1	55
56	1	56
57	1	57
58	1	58
59	1	59
60	1	60
61	1	61
62	1	62
63	n/a	n/a
64	n/a	n/a
65	2	1
66	2	2
67	2	3
68	2	4
69	2	5
70	2	6
71	2	7
72	2	8
73	2	9
74	2	10
75	2	11
76	2	12
77	2	13
78	2	14
79	2	15
80	2	16
81	2	17
82	2	18
83	2	19
84	2	20
85		21
86	2	22
87	2	23

Board Pin	Pin #	I/O slot	Board Pin
47	88	2	24
48	89	2	25
49	90	2	26
50	91	2	27
51	92	2	28
52	93	2	29
53	94	2	30
54	95	2	31
55	96	2	32
56	97	2	33
57	98	2	34
58	99	2	35
59	100	2	36
60	101	2	37
61	102	2	38
62	103	2	39
n/a	104	2	40
n/a	105	2	41
1	106	2	42
2	107	2	43
3	108	2	44
4	109	2	45
5	110	2	46
6	111	2	47
7	112	2	48
8	113	2	49
9	114	2	50
10	115	2	51
11	116	2	52
12	117	2	53
13	118	2	54
14	119	2	55
15	120	2	56
16	121	2	57
17	122	2	58
18	123	2	59
19	124	2	60
20	125	2	61
21	126	2	62
22	127	2	n/a
23	128	2	n/a
*Pins 38-62 are not applicable if I/O slot 1 contains a 37-pin board			

37-pin LAN / COM port— mating connector required: D38999/26WD35PN



Pin number	Pin designation
1	LAN0 TX+ / DA+
2	LAN0 RX+ / DB+
3	LAN0 nc / DC-
4	LAN0 nc / DD+
5	Shield
6	Lan1 TX+ / DA+
7	LAN1 RX+ / DB+
8	LAN1 nc / DC-
9	LAN1 nc / DD+
10	Shield
11	Misc In
12	USB1 P+
13	USB1 D+

Pin designation
USB2 P+
USB2 P-
USB2 D+
USB2 D-
LAN0 TX- / DA-
LAN0 nc / DC+
LAN0 RX- / DB-
LAN0 nc / DD-
LAN1 TX- / DA-
LAN1 nc / DC+
LAN1 RX- / DB-
LAN1 nc / DD-
Misc Out

	1
Pin number	Pin designation
27	USB1 P-
28	USB1 D-
29	Sync Clock Out
30	Sync Trig Out
31	RS232 TX
32	RS232 RX
33	RS232 GND
34	Sync Clock In
35	Sync Trig In
36	Sync +5V
37	Sync Gnd

13-pin power connector — mating connector required: D38999/26FB35PN



Pin #	Pin Designation
1	GND
2	GND
3	GND
4	Vcc (9-36 VDC)
5	Vcc (9-36 VDC)
6	Vcc (9-36 VDC)
7	Sync In2 / reset
8	Sync In0
9	Sync In1
10	Sync Gnd
11	Sync Out1
12	Sync +5V
13	Sync Out0